

Features	
<ul> <li>□ 24,883,200-bit Frame Memory</li> <li>□ 74.25 Mhz Data Rate</li> <li>□ May be Organized Into the Following Configurations:         <ul> <li>□ 3,110,400 x 8-bit</li> <li>□ 2,488,320 x 10-bit</li> <li>□ 2,073,600 x 12-bit</li> </ul> </li> <li>□ Operating Modes:         <ul> <li>□ Random Access with Burst Control</li> <li>• FIFO</li> <li>• Synchronous Shift Register</li> <li>□ Near-Full/Empty Flags With Programmable Thresholds</li> <li>□ Flexible Pointer Manipulation</li> <li>• Write and Read Pointers may be independently jumped to arbitrary address locations</li> <li>• Write or Read Pointers can be manipulated in real-time based on external 24bit address</li> </ul> </li> <li>NOTE: This Preliminary Datasheet references LF332 with an E marking under the part designation.</li> </ul>	□ LF3324s may be Cascaded for depth and width, supporting HDTV, Multiframe SDTV, and other high resolution formats  • Seamless address space is maintained with up to 8 cascaded devices  □ Built-in ITU-R BT.656 TRS detection and Synchronization  □ Set & Clear Read/Write Pointer Control Pine Choice of Control Interfaces:  • Two-wire Serial Microprocessor Interface  • Parallel Microprocessor Interface  □ Input Enable Control (Write Mask) for free frame applications  □ Output Enable Control (Data Skipping)  □ JTAG Boundary Scan - IEEE 1149.1  □ 172 ball LBGA package  □ 1.8V Internal Core Power Supply  □ 3:3V I/O Supply
<ul> <li>□ DTV/HDTV Video Stream Buffer</li> <li>□ Frame Synchronization</li> <li>□ CCTV Security Camera Systems</li> <li>□ Time Base Correction (TBC)</li> <li>□ Freeze-Frame Buffer</li> <li>□ Regional Read/Write for Picture-in-Picture (PIP)</li> <li>□ Field-Based or Frame-Based Comb Filtering</li> <li>□ Video Capture &amp; Editing Systems</li> <li>□ Deep Data Buffering</li> <li>□ Video Special Effects (Rotation, Zoom)</li> <li>□ Test Pattern Generation</li> </ul>	

☐ Motion Detection or Frame-to-Frame Correlation



#### LF3324 Overview

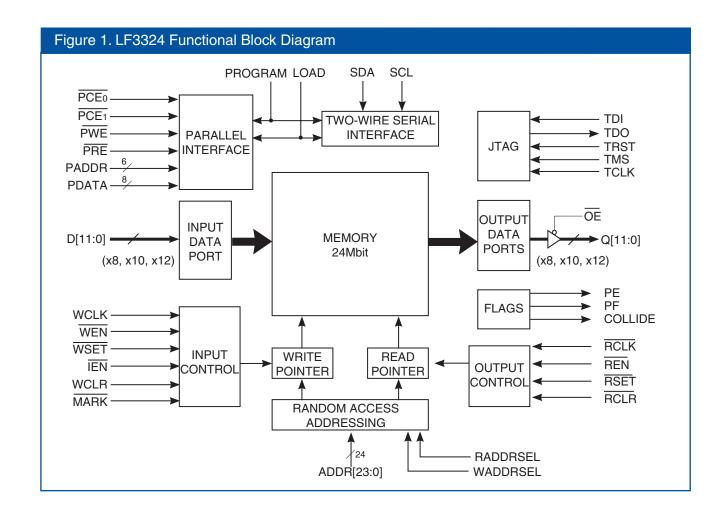
The LF3324 is a 24 Mbit memory device that handles 8, 10, or 12bit data. The input data port may be clocked asynchronously to the output ports. Since reads are non-destructive, a given data value, once written into the memory core, may be read as many times as desired. A user requiring more storage can cascade up to eight LF3324s into a larger array.

A great deal of memory addressing flexibility is offered with the LF3324. Both Burst Mode and Random Access addressing is possible. In addition to simple clearing of the Write and Read pointers, either pointer may be set/jumped to any location within the entire address space. Real-time random-access Writing or Reading is also supported through an external address port.

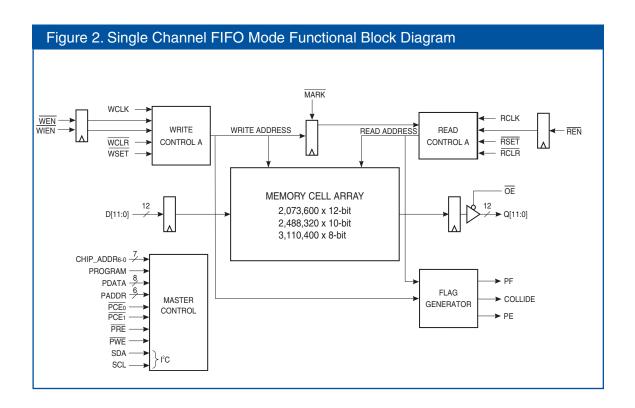
The device is controlled by sixteen instruction words of eight bits each, which may be programmed or verified via standard I<sup>2</sup>C 2-wire serial or parallel microprocessor interfaces.

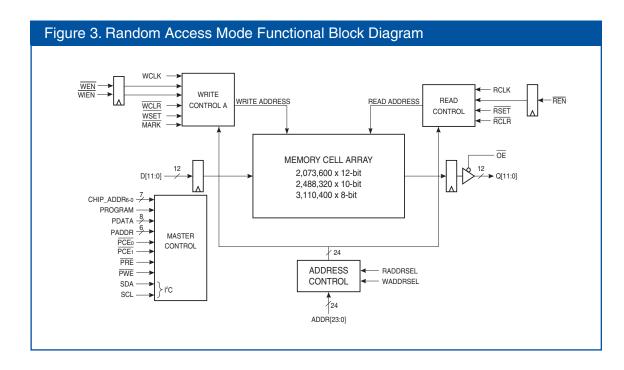
The OPMODE configuration register selects one of the chip's operating modes, each of which has versatile submode options:

- FIFO With Asynchronous I/O
- Synchronous Shift Register (Single Clock; User-set Latency)
- Random Access With Burst Address











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## **Operating Modes**

#### Asynchronous FIFO mode (OPMODE = 3)

In OPMODE 3, the LF3324 is configured as asynchronous First-In-First-Out 24Mbit memory, with independent read and write clocks to allow for asynchronous operation. This mode is ideal for buffering or burst data applications. Arbitrary write/read pointer jumping is supported in all FIFO modes. In this mode the device can re-time a data stream according to a read sync signal (RSET or RCLR) and either ITU-R656 Timing Reference Signals (TRS) embedded within the incoming (video) data or the falling edge of a write sync signal applied to WCLR, WSET, or MARK.

The input (write) and output (read) clocks need not be synchronous with one another, although the memory core may fill or empty if they differ in average frequency. After it "fills," the LF3324 continues writing and the oldest data gets written over. If the memory core "empties" (and neither the read nor write pointer have been set or cleared during run-time) the read pointer stops incrementing, and the device re-reads the last written sample until more data is written. In either case, when the read and write addresses are the same, the COLLIDE flag will go high, to alert the host. The almost-full (PF) and almost-empty (PE) flags provide advance warning of these conditions whenever user-selected "fullness" or "emptiness" thresholds, expressed in approximate eightieths of the memory core size, are exceeded. For example, if the 1/80 and 79/80 thresholds are enabled, flag PE will go HIGH whenever the read pointer lags behind the write pointer by less than 1/80 of the memory space, and flag PF will go HIGH whenever the read pointer leads the write pointer by this amount. (Calculations are performed modulo the total address space.) The data input and output are sequential and the timing between write and read sync signals dynamically determines the effective delay (depth) of the FIFO.

The "stop reading when empty" FIFO-mode behavior can be avoided by making sure LOAD is HIGH and issuing any write or read pointer SET or CLEAR command at any time. This effectively gets the device out of this "read-pointer-halting" mode from that point onwards, but invalidates the flags. Random Access Mode allows free manipulation of the r/w pointers, and never halts the read pointer without being commanded to do so using REN. Since Random Access mode naturally increments the r/w pointers sequentially, like in FIFO mode, it may be a better mode to use if complex pointer manipulation of a single-channel of memory is desired.

#### Synchronous shift register mode (OPMODE = 0)

In OPMODE 0, the LF3324 becomes a shift register with programmable total latency up to 2<sup>24</sup>-8 clock cycles. Writes and reads occur simultaneously, hence synchronous operation.

In OPMODE 0, the user provides a single clock for both the input and output clocks and specifies a desired input-to-output data path latency, <u>config</u>uration register "WADDR" via the control interface. WCLK and RCLK must be tied together, as should WEN and REN. When activated, WADDR will begin to countdown, and once expired, will allow the inputs to begin to appear on the outputs. In OPMODE 0, WADDR countdown can be activated in two ways. The first occurs when the first enable is brought LOW after the LOAD signal has been set HIGH after MPU programming. The second is by bringing LOAD HIGH once MPU programming complete, after the enables have been brought LOW.

#### Random Access Mode (OPMODE = 1)

Random Access mode is a FIFO mode, with the capability of either full-time write or read pointer Random Accessability. This mode also supports write and read pointer jumps to arbitrary locations throughout the address space. Unlike Asynchronous FIFO mode, Random Access mode does not disable memory reads when the read pointer catches up to the write pointer. Write pointer manipulation can be done





## **Operating Modes**

through setting (jumping) the write pointer to the 24bit address via the ADDR[23:0] port or to the WADDR configuration register. Read pointer manipulation can be done through setting (jumping) the write pointer to the 24bit address via the ADDR[23:0] port or to the RADDR configuration register. Periodic write and read pointer jumping can be accomplished by supplying an address through either the ADDR[23:0] external address or the WADDR/RADDR instruction registers. Continuous random access can only be accomplished through the use of the ADDR[23:0] ports. When the write/read pointers are not being set to an address, they increment sequentially in burst mode.

In Random Access Mode, when WADRSEL = 1 and RADRSEL = 0 the write pointer is set to the address supplied by the ADDR[23:0] ports when WSET is brought LOW. In other words, on each active write clock cycle (rising edge of WCLK for which WEN was LOW two rising edges of WCLK previously), the user directs the write pointer to any desired memory location, using what are otherwise the second channel data input and output ports. In this application, ADDR[23:12] denotes the vertical (row) component, and ADDR[11:0], the horizontal (column) component, of a Cartesian set. Setting the configuration register ROW\_LENGTH to the frame's line (row) length internally defines the Cartesian coordinates. Also, ADDR[23:0] can also represent a single 24-bit linear address. The user governs the mapping of (ADDR) to the internal memory space by setting the parameter ROW\_LENGTH such that the internal ADDRESS = ADDR[23-12] \* ROW\_LENGTH + ADDR[11-0]. A ROW\_LENGTH setting of 0 is interpreted as 4096, such that ADDRESS = a 24-bit concatenation of {ADDR} for this particular value. For a standard D1 video application with 1716 samples per line, the user would set ROW\_LENGTH to 1716 decimal = 6B4 hex. Offset circuitry within the LF3324 permits the user to cascade several chips in parallel and to use them collectively as a single large memory with a seamless address space. Data are read out sequentially by rising edges of RCLK, under the control of REN (read enable), RSET (read pointer force to constant), and RCLR (read pointer clear to 0). Holding WSET LOW keeps the device continuously in random access write mode. Releasing WSET to its HIGH state causes the chip to continue to write sequentially from the last-loaded address.

In Random Access Mode, when RADRSEL = 1, WADRSEL = 0, MARK\_SEL = 1, the read pointer is set to the address supplied by the ADDR[23:0] ports when  $\overline{RSET}$  is brought LOW. As mentioned above, ADDR[23:12] represents the upper bits or the vertical (row) address, whereas ADDR[11:0] represents the lower bits or the horizontal (column) address. Releasing RSET HIGH causes the read address pointer to increment from its last assigned location to the next sequential address.

It is important to note that WSET and RSET can be programmed to be level or negative-edge triggered. An edge sensitive "SET" command is useful for using SYNC signals to reset FIFO pointers. Level sensitive "SET" commands allow full-time Random Access capability.





## **Depth Expansion**

#### **Cascading Devices**

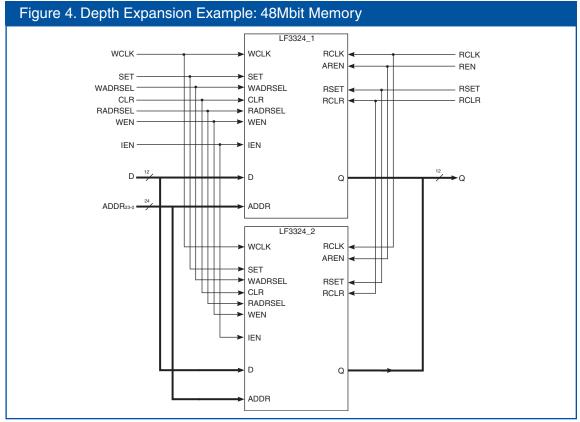
Multiple devices can be cascaded to deepen the address space. For every device cascaded more of the 24bit address space is used.

Internally, the LF3324 has a 24bit address space. The LF3324 was designed to be cascaded in parallel. That is, the inputs of each device are tied together. The input data word (the data word placed on the D input port) is to be common for all devices. Similarly, the outputs of all devices are tied together. Each device's write and read pointers behave identically. Only one device drives the shared output bus at one time, controlled automatically through internal bus enables.

Each device in a cascade of N devices is responsible for 1/N of the address space. That is, each device writes and/or reads based on the common W/R pointer locations and where that particular device sits in the cascade. Configuration Register C[3:0] (BASE\_ADDR) is used to define each device's place in the cascade.

When cascading LF3324s, all write enables WEN and WIEN must be tied together, as must read enables REN (see the device connection diagram below).

The configuration registers of each device must be programmed identically, depending on mode/function, except for Register C. Register C defines which region of the 24bit address space the particular device is responsible for. Within Register C, there is a 4bit BASE\_ADDR and 4bit CASCADE word. BASE\_ADDR determines the region of address space each device controls, and CASCADE defines how many devices are in cascade. Register C effectively is programmed as "Chip n of N".





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## **Device Configuration**

# Programming the LF3324

The LF3324 has two MPU interfaces. The first is a standard two wire serial interface following the I²C protocol. The second is a parallel interface allowing the user to write a byte of data at a time to the configuration registers. When the user wishes to use the serial interface, the PROGRAM pin must be set LOW, while a HIGH selects the parallel interface. To provide users with more flexibility, the control registers have been combined with a "working latch" . Ultimately, the register-latch combination allows users to update the configuration registers during chip operation, and then to transfer the register contents to all working latches simultaneously using the LOAD signal. When high, the LOAD signal allows the LF3324 to be pre-programmed during operation, and once brought low after programming updates the working latches allowing the new changes to take effect. LOAD can also be maintained low to allow changes to the configuration registers to be immediately reflected in the working latches.

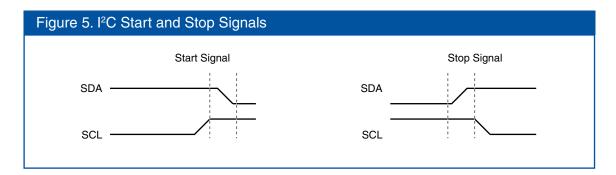
# Serial MPU Interface

When the PROGRAM pin is LOW, the serial interface is active. Up to 8 LF3324 devices can be connected to and programmed by the serial interface. The two wire interface is composed of an SCL clock pin and a bi-directional SDA data pin. When inactive, SDA and SCL are forced HIGH by external pull up resistors.

Data transmission is achieved over the SDA pin and must remain constant during the logical HIGH portion of the SCL clock pulse. The level of SDA, while SCL is HIGH, is interpreted as the appropriate bit value as will be shown later. Changing the data on SDA must only occur when SCL is low, because any changes to SDA while SCL is HIGH is interpreted as a start or stop request, which are shown in Figure 7 with an example data transfer in Figure 8.

The first operation to begin programming the LF3324 through the serial interface, is to send a start signal. When the interface is inactive, a HIGH to LOW transition must be sent on SDA while SCL is HIGH, notifying all connected devices (slaves) to expect a data transmission. When transferring data, the MSB of the eight bit sequence is the first bit to be transmitted to or from the master or slave. The first byte of data to be transmitted on SDA must consist of the 7-bit base address of the slave, along with an 8th READ/WRITE bit as the LSB, which describes the direction of the data transmission. The slave whose 7-bit CHIP\_ADDR6-0, matches the 7-bit base address sent on SDA, will send an acknowledgement back to the master by bringing SDA LOW on the 9th SCL pulse. NOTE: In order to differentiate the two internal die, die 0's CHIP\_ADDR(0) is tied LOW and die 1's CHIP\_ADDR(0) is tied HIGH.

During a write operation, if the slave does not send an acknowledgment back to the master device, SDA is left high which forces the master to generate a stop signal. In contrast, during a read operation, if there is no acknowledgement back from the master device, the LF3324 interprets this as if it were the end of the data transmission, and leaves SDA high, allowing the master to generate its stop signal.

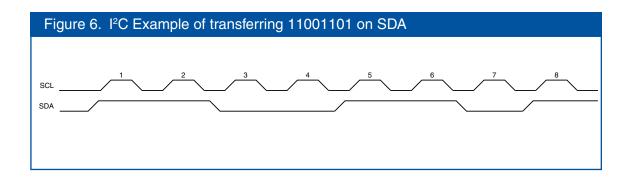




## **Device Configuration**

There are four operations that can be performed between the master and the slave. They are: Write to consecutive registers, write to a single configuration register, read from consecutive registers and read from a single register. To write to consecutive control registers, a start signal and base address must be sent with the R/W bit as described above. After the acknowledgment back from the appropriate slave, the 8-bit address of the target configuration register must be written to the slave with the R/W bit LOW. The slave then acknowledges by setting SDA LOW. The data byte to be written into the register can now be transferred on SDA. The slave then acknowledges by pulling SDA LOW on the next positive going pulse of SCL. The first configuration register address loaded into the LF3324 is considered as the beginning address for consecutive writes, and automatically increments to the next higher address space. Therefore after the acknowledgement, the data byte to configure register (first address + 1) can now be transferred from master to slave. At any point a stop signal can be given to end the data transfer. To write to a single configuration register, the same technique can be applied adding a stop signal after the first data write.

To read from consecutive control registers, the master must again give the start signal followed by a base address with the R/W bit = 0, as if the master wants to write to the slave. The appropriate slave then acknowledges. The master will then transfer the target register address to the slave and wait for an acknowledge. The master will then give a repeated start signal to the slave, along with the base address and R/W bit this time HIGH signifying a read and wait for an acknowledge. The user must write to the LF3324 to select the appropriate initial target register. Otherwise the starting position of the read is uncertain. Once the LF3324 acknowledges, the next byte of data on SDA is the contents of the addressed register sent from the device. If the master acknowledges, the LF3324 will send the next higher register's contents on the following byte of data. To read from only one register is the same procedure as for consecutive reading with a stop signal following the transfer of the register's contents.



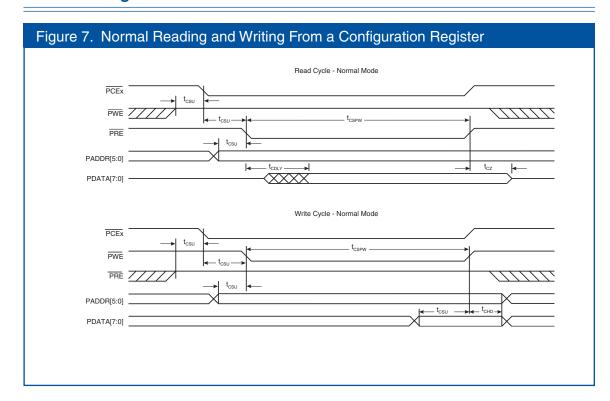
# Parallel MPU Interface

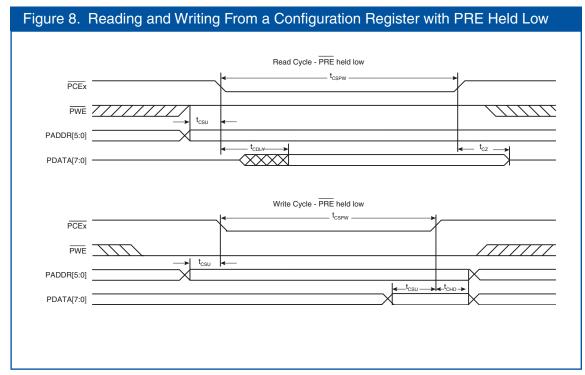
The parallel MPU interface can be used to write instructions to the control registers or to read them back for verification. When the PROGRAM pin is HIGH, the parallel interface is selected. An external processor can write into an internal register by setting PADDR to the desired register address, selecting the chip using the PCEx pin, setting PDATA to the desired value and then pulsing PWE LOW. The data will be written into the selected register when both PWE and PCEx are LOW, and will be held when either signal goes HIGH. To read from a configuration register the processor must set PADDR to the desired address, select the chip with the PCEx pin, and then set PRE LOW. The chip will then drive PDATA with the contents of the selected register. After the processor has read the value from PDATA, PRE and PCEx should be set HIGH. The PDATA pins are turned off (High Impedance) whenever PCEx or PRE are HIGH or when PWE is LOW. The chip will only drive these pins when both PCEx and PRE are LOW and PWE is HIGH. One can also ground the PRE pin and use the PWE pin as a read/write direction control and use the PCEx pin as a control I/O strobe. NOTE: PCE0 addresses die 0, while PCE1 addresses die 1.



## **Device Configuration**

Parallel Interface Cont'd





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## **Detailed Signal Definitions**

#### **Power**

#### VCC<sub>INT</sub> - Internal Core Power Supply

+1.8V power supply. All pins must be connected.

## **VCC**<sub>o</sub>- Output Driver Power Supply

+3.3V power supply. All pins must be connected.

#### **Clocks**

#### WCLK - Write Clock

Data present on D11-0 is written into the LF3324 on the rising edge of WCLK when WEN was LOW for the previous rising edge of WCLK.

#### RCLK - Read Clock

In data is read from the LF3324 and presented on the output port (Q11-0) after a rising edge of RCLK while  $\overline{\text{REN}}$  and  $\overline{\text{OE}}$  are LOW. When using the ADDR[23:0] external address port for read-address setting, ADDR[23:0] is latched on the rising edge or RCLK.

#### Inputs

#### D<sub>11-0</sub> - Data Input

D11-0 is the 12-bit registered data input port. Bit 11 is the MSB in all modes. D1-0 are ignored in 10-bit mode and D3-0 are ignored in 8-bit mode. Any such unused inputs should either be tied to ground or driven to proper logic levels by external logic.

#### ADDR23-0 - Random Access Address Port

ADDR[23:0] is the 24-bit external address port. The 24bit address is a purely linear address when the configuration register ROW\_LENGTH is equal to 0(default). When ROW\_LENGTH is a non-zero value, the memory is set to have a row (line) length of ROW\_LENGTH. ADDR11-0 specifies the X/Column-coordinate and ADDR23-12 specifies the Y/Row-coordinate.

#### CHIP\_ADDR<sub>6-1</sub> - Serial Interface Chip Address

CHIP\_ADDR6- determines the LF3324's address on the two-wire microprocessor bus. Each LF3324 chip's 7-bit two-wire serial microprocessor interface address is equal to its CHIP\_ADDR6-0. NOTE: CHIP\_ADDR0 is internally tied LOW on die 0 and HIGH on die 1.

#### SCL - Serial Clock Input

SCL is a standard two-wire serial microprocessor interface clock pin. With this chip, it functions as a dedicated input, since this part cannot be the master on an two-wire serial microprocessor interface.

#### PADDR<sub>5-0</sub> - Parallel Microprocessor Interface Address Port

PADDR5-0 is the 6-bit address port for the parallel microprocessor interface.

## Input/Output

## PDATA<sub>7-0</sub> - Parallel Microprocessor Interface Data Port

PDATA7-0 is the 8-bit data port for the parallel microprocessor interface. When inactive becomes high impedance.

#### SDA - Serial Data I/O

SDA is the standard bidirectional data pin of a two-wire serial microprocessor interface. External pullup is required on SDA.

#### **Controls**

#### WCLR - Write Pointer Clear

When  $\overline{WCLR}$  is brought LOW, the next rising edge of WCLK will bring the current value on D[11:0] into memory address 0. Whenever  $\overline{WCLR}$  is HIGH, the destination for D[11:0] will be controlled by  $\overline{WSET}$ . The user may program  $\overline{WCLR}$  such that either its falling edge or its LOW state is active. If its LOW state





## **Detailed Signal Definitions**

is active, holding this pin LOW will hold the write address in its zero position continuously. This control takes effect only when  $\overline{\text{WEN}}$  is LOW.

#### RADDRSEL - Read Address Select

<u>RADD</u>RSEL selects the source of the read address. This pin and control MARKSEL select whether RSET forces the read address to the RADDR configuration register (RADDRSEL = 0) or to ADDR[23:0] (RADDRSEL = 1). This control takes effect only when  $\overline{REN}$  is LOW.

#### WSET - Write Pointer Set

This control is active only when WCLR is HIGH. Bringing WSET LOW will cause the next rising edge of WCLK to bring the current value on D[11:0] into memory at the address specified by WADDR, or at the address present on ADDR[23:0]. Whenever WSET and WCLR are HIGH, the next rising edge of WCLK will bring the current D[11:0] data value into the next-higher address in sequence. WSET may be programmed to be either edge-triggered, in which case it affects the write pointer for only one clock cycle following a falling edge, after which incrementing resumes, or level-triggered, in which case it affects the write pointer until it is brought HIGH. For continuous random access write operation, holding WSET LOW and programming it to be level-triggered will provide the needed continuous write pointer override. This control takes effect only when WEN is LOW.

#### WADDRSEL - Write Pointer Set

WADDRSEL selects the source of the write address. WADDRSEL determines whether WSET forces the write address pointer to the WADDR configuration register (WADDRSEL = 0) or to ADDR[23:0] (WADDRSEL = 1). This control takes effect only when  $\overline{\text{WEN}}$  is LOW.

#### MARK - Write Address Pointer Mark

Bringing this bit LOW will cause an internal register to store a copy the current value of the write address pointer, for subsequent use in synchronizing the corresponding read address pointer to the same location. Unlike WCLR and WSET, this control does not affect the write pointer value itself. The system must use MARK instead of WCLR if the entire memory core can be filled between sequential falling edges of the sync reference signal. In contrast, the system must use WCLR or WSET to establish a definite relationship between the internal address and the data stream, as in random access read mode.

#### RSET - Read Address Pointer Set

If REN is LOW, bringing RSET LOW will force the read address to the most recently marked value (MARK\_SEL LOW), to RADDR (MARKSEL HIGH and RADRSEL LOW), or to ADDR[23:0] (MARK\_SEL is HIGH and RADRSEL is HIGH). This pin may be programmed to be either falling edge or level sensitive active.

#### RCLR - Read Address Pointer Clear

Bringing RCLR LOW causes the next rising edge of RCLK to force the read address pointer to zero. This pin may be programmed to be active on its falling edge or in its LOW state. It can reset the read pointer only when REN is LOW.

#### WEN - Write Enable

If WEN is LOW, data on D11-0 is written to the device on the rising edge of WCLK. When WEN is HIGH, the device ignores data on D and holds the write pointer. The user must anticipate the use of WEN by one cycle. Therefore when desiring not to write a sample, WEN must be brought high the cycle before.

#### WIEN - Memory Write Enable (Write Masking)

WIEN is used to enable/disable writing into the memory core. A LOW on WIEN enables writing, while a HIGH on  $\overline{\text{WIEN}}$  disables writing. The internal write address pointer is incremented by  $\overline{\text{WEN}}$  regardless of the  $\overline{\text{WIEN}}$  level. If disabling of  $\overline{\text{WIEN}}$  is never desired, tie  $\overline{\text{WIEN}}$  LOW.





## **Detailed Signal Definitions**

#### REN - Read Enable

If REN is LOW and the output port is enabled, data is read and presented on Q[11:0] after to has elapsed from the rising edge of RCLK. If REN goes HIGH, the last value loaded into output register will remain unchanged and the read pointer will be held. The user must anticipate the use of REN by one cycle. Therefore when desiring not to read a sample, REN must be brought high the cycle before.

#### PROGRAM - Serial/Parallel Interface Selector

When the user wishes to use the serial microprocessor to configure the LF3324, the PROGRAM pin must be set LOW. If the user wishes to use the parallel interface, PROGRAM must be set HIGH.

#### LOAD - Instruction Load

Bringing asynchronous control LOAD LOW updates the working instruction latches to match the current contents of the instruction preload latches. Holding it LOW causes the working latches to reflect all ongoing instruction preloads. Holding it HIGH permits the user to preset the instruction preload latches to any desired configuration without disturbing the work in progress. After any write to the configuration registers, LOAD must be brought high for one cycle, and can then be brought and left low if so desired.

#### RESET - Global Reset

Bringing synchronous control RESET LOW forces all state machines and read and write pointers to 0 and holds them there until it is released HIGH. It also forces the configuration registers to their default states, if and only if LOAD is also LOW. The user may then modify the control registers as necessary. Bringing RESET LOW while holding LOAD HIGH will reset the state machines and pointers, but will not change either the preload or the working latches.

#### OE - Output Enable

When  $\overline{\text{OE}}$  is LOW, Q[11:0] is enabled for output. When OE is HIGH, Q[11:0] is placed in a high-impedance state. In 10-bit modes, Q1-0 are unconditionally tristated. In 8-bit modes, Q3-0 are tristated. The flag outputs are not affected by  $\overline{\text{OE}}$ .

#### PCE<sub>0</sub>/PCE<sub>1</sub> - Parallel Interface Chip Enable

When LOW, PCE<sub>0</sub> enables writing to die 0 with the parallel micrprocessor interface. When LOW, PCE<sub>1</sub> enables writing to die 1 with the parallel micrprocessor interface.

#### PWE - Parallel Interface Write Enable

When LOW, PWE enables writing to the LF3324's Instruction Registers with the parallel micrprocessor interface.

#### PRE - Parallel Interface Read Enable

When LOW, PRE enables reading from the LF3324's Instruction Registers with the parallel micrprocessor interface.

#### **Data Outputs**

#### Q<sub>11-0</sub> - Data Output

Q[11:0] is the 12-bit registered data output port. Q[11:0] is always the MSB. In 10-bit mode, bits 1 and 0 are tristated. In 8-bit mode, bits 3-0 are tristated. All active bits are updated on each rising edge of RCLK when  $\overline{\text{REN}}$  is LOW.





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## **Detailed Signal Definitions**

### **Flag Outputs**

#### PF - Programmable Almost Full

PF goes HIGH (active) when the write pointer is more than (MAX\_depth - (MAX\_depth x TH)) locations ahead of the read pointer. TH is a threshold value stored in Register 9 [2:0]. PF is updated on the rising edge of WCLK. TRS bits either entering of emerging to/from the device can be mapped to PF (Register B[3:0]).

#### PE - Programmable Almost Empty Flag

PE goes HIGH (active) when the write pointer is less than or equal to (MAX\_depth - (MAX\_depth x TL)) locations ahead of the read pointer. TL is a threshold value stored in Register 9 [2:0]. PE is updated on the rising edge of RCLK. TRS bits either entering of emerging to/from the device can be mapped to PE (Register B[7:4]).

#### COLLIDE - Memory Read/Write Pointer Collision Flag

This flag goes high whenever the read and write addresses to the memory core coincide. By monitoring the partial full/empty flags, the user can ascertain the direction of approach, i.e., read pointer catching up with write (FIFO empty) or write pointer catching up with read (FIFO full). TRS bits from D and Q can be mapped to COLLIDE (Register B[3:0]).

#### **JTAG**

#### TDI - JTAG input data

TDI is the input data pin when using JTAG.

#### TDO - JTAG output data

TDO is the output data pin when using JTAG.

#### TRSTB - JTAG reset

TRSTB is used to reset all the registers and state machine fount the the JTAG module.





## **Detailed Signal Definitions**

#### TMS - JTAG Tap controller input

TMS controls the state of the tap controller.

#### TCK - JTAG clock

TCK is the used supplied clock of JTAG. It controls the flow of data and latches input data on the rising edge.

## **Configuration Register Map**

The various 8-bit control registers may be pre-programmed with either the parallel microprocessor port (PROGRAM=1), or through the serial microprocessor interface bus(PROGRAM=0). Changes in pre-programming begin to affect the data path when  $\overline{\text{LOAD}}$  is brought LOW. In each instance, the value in parens () is the default state following assertion of RESET while  $\overline{\text{LOAD}} = 0$ .

#### Configuration Register 0 (default = 00000000)

#### Configuration Register 1 (default = 00000000)

$7:0 = ROW_LENGTH[7:0]$	(00000000: 24-bit linear map; see reg 6)

#### Configuration Register 2 (default = 00000000)

7:0 = WADDR[23:16] (00000000: default = 0; see reg 9, a)
--

#### Configuration Register 3 (default = 00000000)

7:0 = WADDR[15:8]	(00000000: default = 0; see reg 8, a)
-------------------	---------------------------------------

#### Configuration Register 4 (default = 00000000)

7:0 = WADDR[7:0] (00000000: default = 0; see reg 8, 9)	
--	--

#### Configuration Register 5 (default = 00000000)

7:0 = RADDR[23:16]	(0000000)
--------------------	-----------

### Configuration Register 6 (default = 00000000)

7:0 = RADDR[15:8] (00000000)	
------------------------------	--

#### Configuration Register 7 (default = 00000000)

7:0 = RADDR[7:0] (00000000)	
-----------------------------	--

## **Configuration Register Map**

### Configuration Register 8 (default = 10\_00\_0\_111)

7:6 = WIDTH[1:0]	(10: 10 bits)
5:4 = Reserved	(Make equal to 00)
3 = MARK_ACTIVE_RSET	(Make equal to 0)
2:0 = OPMODE	(111)

### Configuration Register 9 (default = 00\_000\_000)

7:6 = TRS_SYNC[1:0]	(00: ignore embedded TRS)
5 =	Reserved - set to 0
4 = A_FLD	(0: frame sync - use falling F-bit from TRS)
3 = MARK_SEL	(0: use marked address - not user defined address)
2:0 = FLAG_SET	(000: trigger empty, full on 1/80, 79/80)

#### Configuration Register A (default = 00000000)

7 =	Reserved - set to 0
6 = WSET_catch	(0: setting pointer does not MARK its new value)
5 = RSET_b_sel	(0: RSET is falling edge triggered)
4 = RCLR_b_sel	(0: RCLR is falling edge triggered)
3 =	Reserved - set to 0
2 =	Reserved - set to 0
1 = WSET_b_sel	(0: WSET is falling edge triggered)
0 = WCLR_b_sel	(0: WCLR is falling edge triggered)

## Configuration Register B (default = 00\_00\_00\_00)

7:4 =	RESERVED
3:0 = FLAG_CTL	(00: PE, PF are part-empty, -full)

## Configuration Register C (default = 0000\_0000)

7:4 = BASE_ADDR	(0000: lowest-address chip in cascade sequence)
3:0 = CASCADE	(0000: single chip - no cascade of multiple chips)



#### Register 0[3:0], Register 1[7:0] = ROW LENGTH[11:0] - for Cartesian-to-linear address map

This control governs the remapping of Cartesian coordinates arriving on ADDR[11-0] (horizontal/column component) and ADDR[23-12] (vertical/row component) into a linear address, for use by the chip's internal address generator. Setting ROW\_LENGTH to 0 causes the incoming address to be interpreted directly as a linear address, with the 24bits ADDR[23:0] address.

# Register 2[7:0], Register 3[7:0], Register 4[7:0] = WADDR[23:0] - Shift Register Latency or 24bit 'Jump' Address

Configuration register WADDR determines the effective shift register depth, i.e., such that the chip's input-to-out latency = TBD + (WADDR clock cycles). For OPMODE = 0, a falling edge on pin MARK registers the current value of the write pointer and starts a countdown timer, which forces the read pointer to this registered value WADDR clock cycles later. The maximum delay that WADDR can be made equal to is  $2^{24}$ -2 clock cycles.

In addition to this function bringing WSET LOW forces/jumps the memory write pointer to the address defined by WADDR (when WADRSEL is LOW). Thus, when WADDR is used to establish a time delay, it is interpreted as an ordinary unsigned binary number. In contrast, when it is used to override an address pointer, WADDR defines an address. When ROW\_LENGTH is a non-zero value, WADDR[11:0] is equal to the 12-bit X-coordinate (Horizontal) and WADDR[23:12] is considered the Y-coordinate (Vertical) in a Cartesian Coordinate system. When ROW\_LENGTH is 0, WADDR[23:0] is considered to be a linear address in the memory space. By changing the ROW\_LENGTH, the X-coordinate can be from 0 to (ROW\_LENGTH-1) to make up the Cartesian plane. For example, if ROW\_LENGTH = 16, the X-coordinate or WADDR[11:0] can be from 0 to 15 in the Cartesian space.

#### Register 5[7:0], Register 6[7:0], Register 7[7:0] = RADDR[23:0] - 24bit 'Jump' Address

Bringing RSET LOW forces/jumps the read pointer to the address defined by RADDR.

#### Register 8[7:6] = WIDTH[1:0] - data word size at input/output ports

		Input Port	Output Port
0x	8 bits	D[11:4]	Q[11:4] (Q[3:0] tristated)
10	10 bits	D[11:2] (default)	Q[11:2] (Q[1:0] tristated)
11	12 bits	D[11:0]	Q[11:0]

#### Register 8[5:4] = Reserved

#### Register 8[3] = MARK\_ACTIVE\_RSET

0	ignores the internal RSET that occurs following the MARK
1	obeys the internal RSET according to the MARK



#### Register 8[2:0] = OPMODE[2:0] - operating mode

000	Synchronous Shift Register
001	Random Access
010	RESERVED
011	Asynchronous FIFO
1XX	RESERVED

## Register 9[7:6] = TRS\_SYNC[1:0] - response to embedded TRS EAV

00	disable TRS sync detection (default)
01	F-bit of embedded TRS EAV marks current write pointer.
10	F-bit of embedded TRS EAV sets current write pointer to value set by ADDR[23:0] or WADDR
11	RESERVED

### Register 9[4] = FLD frame/field sync select

0	use only falling F-bit in EAV (frame-based sync); ignore rising F-bit (default)
1	use both rising and falling F-bit in EAV (field-based sync)

# Register 9[3] MARK\_SEL - This signal is used in combination with pin RADRSEL to determine to effect of bringing RSET low on the read pointer(s). When RSET goes to 0:

0	force read pointer(s) to marked address(es) (default)
1	force read pointer(s) as shown in following table:

	RADRSEL	Read Pointer I	Eauals:
--	---------	----------------	---------

1	ADDR[23:0] address
0	RADDR address



Register 9[2:0] = FLAG\_SET[2:0] - sets fractional "fullness" and "emptiness" thresholds in memory core.

Partially Full flag goes HIGH when the memory is more than "TH" full. Partially Empty flag goes HIGH when the memory is less than or equal to "TL" full.

000	TH = 79/81 (default)	TL = 1/81 (default)
001	TH = 78/81	TL = 2/81
010	TH = 77/81	TL = 3/81
011	TH = 76/81	TL = 4/81
100	TH = 75/81	TL = 5/81
101	TH = 74/81	TL = 6/81
110	TH = 73/81	TL = 7/81
111	TH = 72/81	TL = 8/81

#### Register A[6] = WSET\_catch

0	Setting Write Pointer does not "MARK" its new value (default)
1	Setting Write Pointer auto-MARKS its new value

## Register A[5:0] Control action.

Rb[5]	RSET_b_sel
Rb[4]	RCLR_b_sel
Rb[3]	WADDRSEL_b_sel
Rb[2]	RADDRSEL_b_sel
Rb[1]	WSET_b_sel
Rb[0]	WCLR_b_sel
if 0:	Each falling edge on the corresponding control pin overrides a
	memory address counter for exactly one clock cycle, after which
	normal memory address incrementing immediately resumes. (default)
if 1:	The corresponding pin continuously overrides the memory address
	counter as long as it is held LOW. Memory address incrementing
	resumes when the pin is returned HIGH.

#### Register B[7:4]=

	Reserved
--	----------



#### Register B[3:0] FLAG\_CTL[3:0] for pins PE and PF \*

FLAG_CTL	TL PE PF		COLLIDE	
0000	Empty (Emerging)	Full (Incoming)	COLLIDE (Emerging)	
0001		RA=MA (Emerging)	COLLIDE (Emerging)	
0010	D f (Incoming)	D v (Incoming)	D h (Incoming)	
0011	0011 Qf (Emerging) Qv (Emerging) Qh (Emerg			
0100	Df (Incoming)	D v (Incoming) COLLIDE (Emerging		
0101	Q f (Emerging)	Q v (Emerging)	COLLIDE (Emerging)	
0110	D f (Incoming)	D h (Incoming)	COLLIDE (Emerging)	
0111	Q f (Emerging)	Q h (Emerging)	COLLIDE (Emerging)	
1000	D v (Incoming)	D h (Incoming)	COLLIDE (Emerging)	
1001	Q v (Emerging)	Q h (Emerging)	COLLIDE (Emerging)	

<sup>\*</sup>Each flag is updated on the rising edge of its associated clock: WCLK (Incoming) or RCLK (Emerging)

MA is the 'marked' address pointer value.

# Register C[7:4] = BASE\_ADDR[3:0] - position of chip in cascade series; 0000 = lowest; BASE\_ADDR[3:0] must not exceed CASCADE[3:0]\*\*

0000:	chip one of N (N is number of chips in system)		
0001:	chip two of N (N is number of chips in system)		
0111:	chip eight of N (N is number of chips in system)		

<sup>\*\*</sup> Note: There are two cascaded die per LF3324. Die 0 is chip 1 of 2, die 2 is chip 2 of 2.

# Register C[3:0] = CASCADE[3:0] - number of chips in a system with concatenated address spaces\*.

0001:	single chip operation (two die)		
0011:	two chip cascade (four die)		
1111:	eight chip cascade (sixteen die)		

<sup>\*</sup> Note limits regarding the number of possible chips, related to WIDTH control:

8bit data: 5 or less LF3324s (WIDTH = 0x) 10bit data: 6 or less LF3324s (WIDTH = 10) 12bit data: 8 or less LF3324s (WIDTH = 11)



D f, v, h are the TRS bits embedded in the incoming TRS signals.

Q f, v, h are the TRS bits embedded in the emerging TRS signals.

RA is the read address pointer value.



# **Reserved Configuration Registers**

Instruction registers D hex and above are reserved for test purposes only.







## MAXIMUM RATINGS Above which useful life may be impaired (Notes 1, 2, 3, 8)

Storage temperature  $-65^{\circ}\text{C}$  to  $+150^{\circ}\text{C}$   $\text{VCC}_{\text{INT}}$ , Internal supply voltage with respect to ground -0.5V to +2.0V VCC<sub>O</sub>, Output drivers supply voltage with respect to ground -0.5V to +4.0V Signal applied to high impedance output -0.5V to +3.3V Output current into low outputs 25 mA Latchup current  $-65^{\circ}\text{C}$  to  $+150^{\circ}\text{C}$  to +2.0V -0.5V to +3.3V Output current into low outputs -0.5V to +3.3V

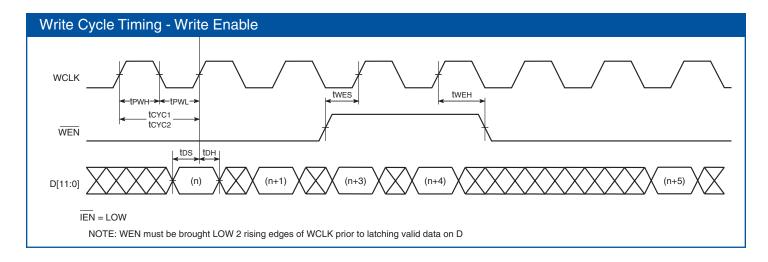
## **OPERATING CONDITIONS** To meet specified electrical and switching characteristics

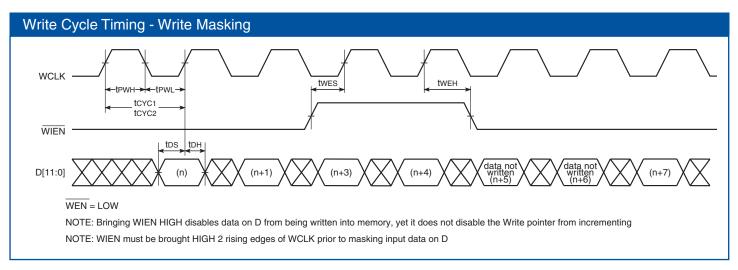
CharacteristicModeTemperature RangeSupply Voltage $VCC_{INT}$ Commercial0°C to +70°C $1.71V \le Vcc \le 1.89V$  $VCC_{O}$ Commercial0°C to +70°C $3.00V \le Vcc \le 3.60V$ 

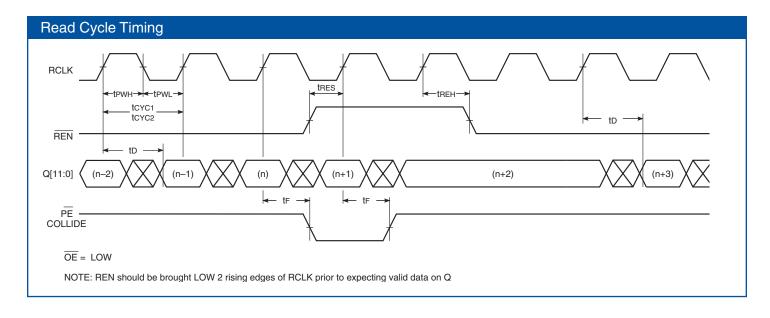
ELECTRICAL CHARACTERISTICS Over Operating Conditions (Note 4)						
Symbol	Parameter	Test Condition	Min	Тур	Max	Unit
<b>V</b> OH	Output High Voltage	Vcc = Min., IOH MAX = -4 mA	2.4			V
<b>V</b> OL	Output Low Voltage	Vcc = Min., Iol MAX = 4 mA			0.4	V
<b>V</b> IH	Input High Voltage		2.0			V
<b>V</b> IL	Input Low Voltage	(Note 3)			0.8	V
lix	Input Current	With Internal Pull-up - JTAG			+20	μΑ
lix	Input Current	All other pins			±10	μΑ
loz	Output Leakage Current Ground ≤ VouT ≤ Vcc (Note 12) ±		±10	μΑ		
ICC1	<b>V</b> cc Current, Dynamic	(Note 5,6)	400 mA		mA	
ICC2	Vcc Current, Quiescent (Note 7)		10	mA		
CIN	Input Capacitance	<b>T</b> A = 25°C, f = 1 MHz			7	pF
Соит	Output Capacitance T <sub>A</sub> = 25°C, f = 1 MHz				7	pF

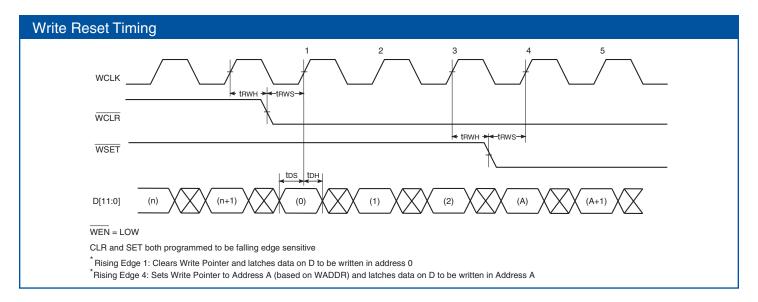


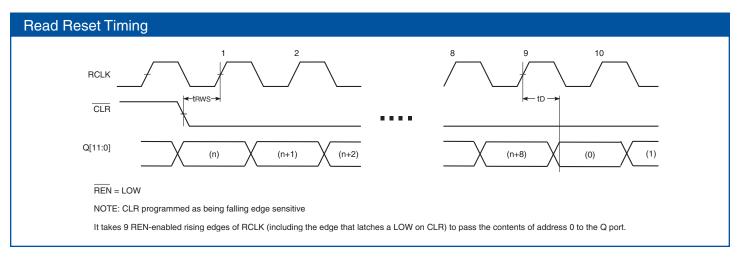
Switching Characteristics						
Commercial Operating Range (0°C to +70°C) Notes 9, 10 (ns)						
		LF3324BGC				
Symbol	Parameter Min N		Max	Max Min		
<b>t</b> CYC1	Cycle Time 1 (WCLK, RCLK) - FIFO / Sh. Reg Modes	13.4				
<b>t</b> CYC2	Cycle Time 2 (WCLK, RCLK) - Full-time Random Access	18				
<b>t</b> PWH	Clock Pulse Width High (WCLK, RCLK)	5				
<b>t</b> PWL	Clock Pulse Width Low (WCLK, RCLK)	5				
<b>t</b> ds	Setup Time, Data Inputs (D)	5				
<b>t</b> DH	Hold Time, Data Inputs (D)	1				
<b>t</b> wes	Write Enable Setup Time (WEN)	5				
<b>t</b> WEH	Write Enable Hold Time (WEN)	1				
<b>t</b> res	Read Enable Setup Time (REN)	5				
<b>t</b> reh	Read Enable Hold Time (REN)					
<b>t</b> lds	Load Setup Time 5					
<b>t</b> ldh	Load Hold Time	1				
<b>t</b> rws	R/W Set/Clr Setup Time	5				
<b>t</b> rwh	(WCLR,RADDRSEL,WSET,WADDRSEL,RSET,RCLR)	1				
<b>t</b> D	R/W Set/Clr Hold Time		7			
<b>t</b> F	(WCLR,RADDRSEL,WSET,WADDRSEL,RSET,RCLR)		7			
<b>t</b> dis	Access Time		10			
<b>t</b> ENA	Write Clock to Programmable Flags (PE, PF, COLLIDE)		10			
<b>t</b> csu	Tri-state Output Disable Delay	5				
<b>t</b> CHD	Tri-state Output Enable Delay	1				
<b>t</b> cspw	Parallel Interface Control Setup Time for Reads/Writes	20				
<b>t</b> CDLY	Parallel Interface Control Hold Time for Reads/Writes		8			
<b>t</b> cz	Parallel Interface Control Strobe Pulse Width		10			
	Parallel Interface Control Output Delay					
	Parallel Interface Control Tristate Delay					

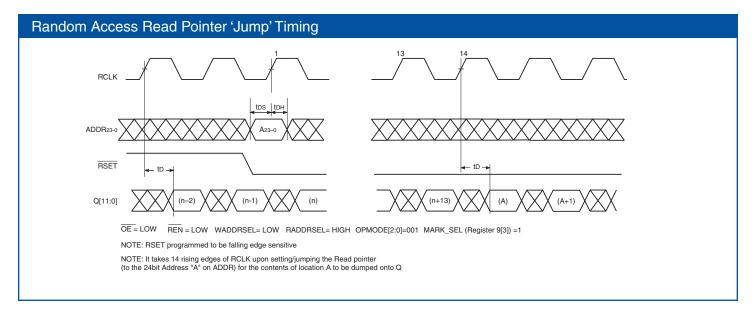


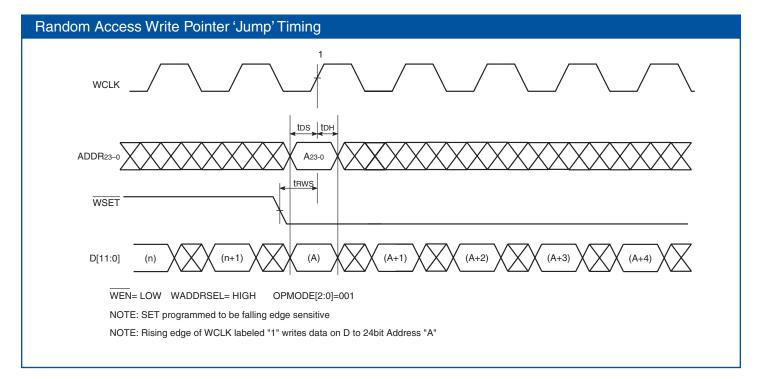


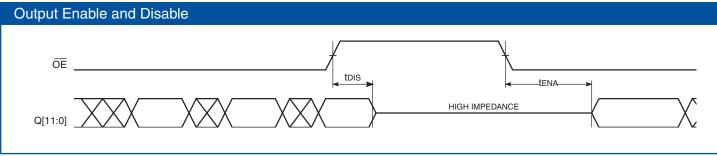


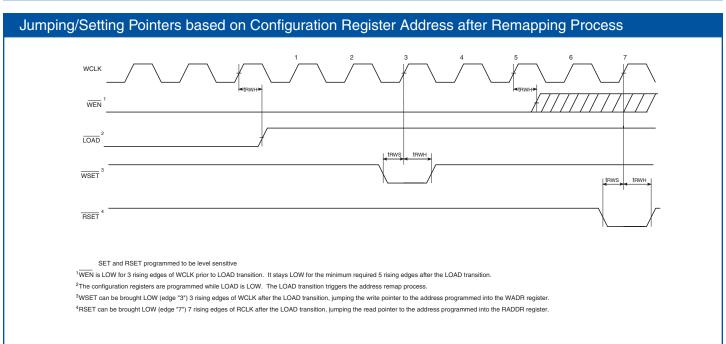












#### **Notes**

- 1. Maximum Ratings indicate stress specifications only. Functional operation of these products at values beyond those indicated in the Operating Conditions table is not implied. Exposure to maximum rating conditions for extended periods may affect reliability.
- 2. The products described by this specification include internal circuitry designed to protect the chip from damaging substrate injection currents and accumulations of static charge. Nevertheless, conventional precautions should be observed during storage, handling, and use of these circuits in order to avoid exposure to excessive electrical stress values.
- 3. This device provides hard clamping of transient undershoot. Input levels below ground will be clamped beginning at -0.6 V. The device can withstand operation with inputs or outputs in the range of -0.5 V to +5.5 V. Device operation will not be adversely affected, however, input current levels may be in excess of 100 mA.
- 4. Actual test conditions may vary from those designated but operation is guaranteed as specified.
- 5. Supply current for a given application can be approximated by:

where  $\frac{NCV^2F}{2}$ 

N = total number of device outputs

C = capacitive load per output

V = supply voltage F = clock frequency

6. Tested with outputs changing every cycle and no load, at a 50 MHz clock rate.

- 7. Tested with all inputs within 0.1 V of VCC or Ground, and no load.
- 8. These parameters are guaranteed but not 100% tested.
- 9. AC specifications are tested with input transition times less than 3 ns, output reference levels of 1.5 V (except t<sub>dis</sub> test), and input levels of nominally 0 to 3.0V. Output loading may be a resistive divider which provides for specified IOH and IOL at an output voltage of VOH min and VOL max respectively. Alternatively, a diode bridge with upper and lower current sources of IOH and IOL respectively, and a balancing voltage of 1.5 V may be used. Parasitic capacitance is 30 pF minimum, and may be distributed.

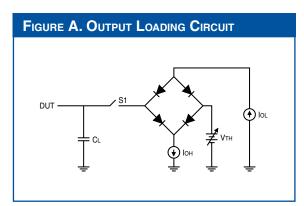
This device has high-speed outputs capable of large instantaneous current change pulses and fast turn-on/turn-off times. As a result, care must be exercised in the testing of this device. The following measures are recommended:

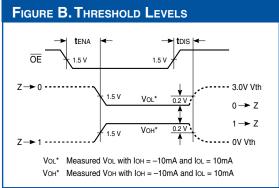
- a. A 0.1 μF ceramic capacitor should be installed between VCC and Ground leads as close to the device as possible. Similar capacitors should be installed between device VCC and the tester common, and device ground and tester common.
- b. Ground and VCC supply planes must be brought directly to the device leads.
- c. Input voltages on a test fixture should be adjusted to compensate for inductive ground and **VCC** noise to maintain required input levels relative to the device ground pin.



#### **Notes**

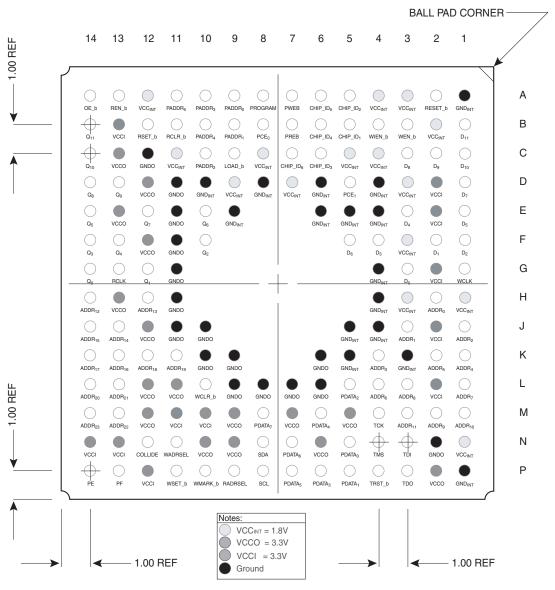
- 10. Each parameter is shown as a minimum or maximum value. Input requirements are specified from the point of view of the external system driving the chip. Setup time, for example, is specified as a minimum since the external system must supply at least that much time to meet the worst-case requirements of all parts. Responses from the internal circuitry are specified from the point of view of the device. Output delay, for example, is specified as a maximum since worst-case operation of any device always provides data within that time.
- 11. For the  $t_{ena}$  test, the transition is measured to the 1.5 V crossing point with datasheet loads. For the  $t_{dis}$  test, the transition is measured to the  $\pm 200$ mV level from the measured steady-state output voltage with  $\pm 10$ mA loads. The balancing voltage,  $V_{th}$ , is set at 3.0 V for Z-to-0 and 0-to-Z tests, and set at 0 V for Z-to-1 and 1-to-Z tests.
- 12. These parameters are only tested at the high temperature extreme, which is the worst case for leakage current.







## Package and Ordering Information



172 Ball - Low Profile Ball Grid Array (LBGA)

0°C to 70°CCommercial Screening			
Speed			
_	LF3324BGC		

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## **Document History Page**

DOCUMENT TITLE: LF3324 24MBIT FRAME BUFFER / FIFO					
Rev.	ECN NO.	Issue Date	Description of Change		
А		03/08/05	Initiate		
В		03/28/05	Downgraded part speed from 12ns to 13.5ns		
С		04/07/05	Upgraded Speed from 13.5ns to 13.4ns		
			Fixed incorrect description of the program pin on page 14		
			Added data rate		
D		08/18/05	Clarified Programmable FLAG operation text		
Е		09/14/05	Clarified FIFO operation text		

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